

TDA7561

MULTIFUNCTION QUAD POWER AMPLIFIER WITH BUILT-IN DIAGNOSTICS FEATURES

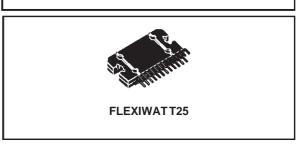
- DMOS POWER OUTPUT
- HIGH OUTPUT POWER CAPABILITY 4x25W/4Ω @ 14.4V, 1KHZ, 10% THD, 4x35W EIAJ
- MAX. OUTPUT POWER 4x60W/2Ω
- FULL I2C BUS DRIVING:
 - ST-BY
 - INDEPENDENT FRONT/REAR SOFT PLAY/MUTE
 - SELECTABLE GAIN 26dB 12dB (FOR LOW NOISE LINE OUTPUT FUNCTION)
 - I²C BUS DIGITAL DIAGNOSTICS
- FULL FAULT PROTECTION
- DC OFFSET DETECTION
- FOUR INDEPENDENT SHORT CIRCUIT PROTECTION
- CLIPPING DETECTOR
- ESD PROTECTION

DESCRIPTION

The TDA7561 is a new BCD technology QUAD BRIDGE type of car radio amplifier in Flexiwatt25 package specially intended for car radio applications.

MULTIPOWER BCD TECHNOLOGY

MOSFET OUTPUT POWER STAGE

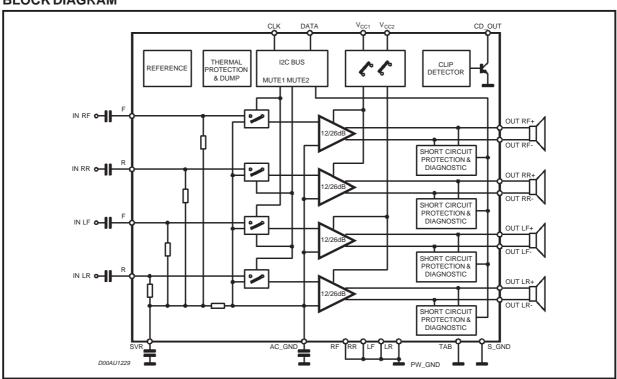


Thanks to the DMOS output stage the TDA7561 has a very low distortion allowing a clear powerful sound.

This device is equipped with a full diagnostics array that communicates the status of each speaker through the I²C bus.

The possibility to control the configuration and behaviour of the device by means of the I²C bus makes TDA7561 a very flexible machine.

BLOCK DIAGRAM



January 2002 1/18

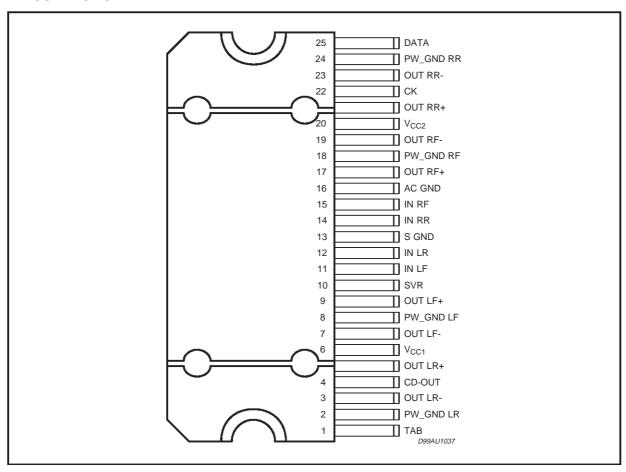
ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{op}	Operating Supply Voltage	18	V
Vs	DC Supply Voltage	28	V
V _{peak}	Peak Supply Voltage (for t = 50ms)	50	V
V _{CK}	CK pin Voltage	6	V
V _{DATA}	Data Pin Voltage	6	V
lo	Output Peak Current (not repetitive t = 100μs)	8	Α
Io	Output Peak Current (repetitive f > 10Hz)	6	Α
P _{tot}	Power Dissipation T _{case} = 70°C	85	W
T _{stg} , T _j	Storage and Junction Temperature	-55 to 150	°C

THERMAL DATA

	Symbol	Description		Value	Unit
ı	R _{th j-case}	Thermal Resistance Junction-case		1	°C/W

PIN CONNECTION



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Vcc1 Vcc2 17 OUT RF 25 18 I²C BUS 19 21 C1 0.22µF 22 OUT RR IN RF 15 23 C2 0.22μF 9 IN RR **5** 14 OUT LF 8 C3 0.22μF IN LF 11 5 OUT LR C4 0.22μF 2 IN LR 3 12 S-GND TAB 13 10 47K C6 C5 10μF $1\mu\text{F}$ CD OUT D00AU1212

Figure 1. Test and Application Circuit

ELECTRICAL CHARACTERISTICS (Refer to the test circuit, Vs = 14.4V; RL = 4Ω ; f = 1KHz; Tamb = 25°C; unless otherwise specified.)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
POWER AI	MPLIFIER					
Vs	Supply Voltage Range		8		18	V
ld	Total Quiescent Drain Current			150	300	mA
Po	Output Power	EIAJ (Vs = 13.7V)	32	35		W
		THD = 10% THD = 1%	22	25 20		W W
		$R_L = 2\Omega; EIAJ (Vs = 13.7V)$ $R_L = 2\Omega; THD 10\%$ $R_L = 2\Omega; THD 1\%$ $R_L = 2\Omega; MAX POWER$	50 32	55 38 30 60		W W W
THD	Total Harmonic Distortion	Po = 1W to 10W;		0.04	0.1	%
		$G_V = 12dB; V_O = 0.1 \text{ to } 5V_{RMS}$		0.02	0.05	%
Ст	Cross Talk	$f = 1KHz$ to $10KHz$, $R_G = 600\Omega$	50	60		dB
Rin	Input Impedance		80	100	130	ΚΩ
Gv1	Voltage Gain 1		25	26	27	dB
∆Gv1	Voltage Gain Match 1		-1		1	dB
Gv2	Voltage Gain 2		11	12	13	dB
∆Gv2	Voltage Gain Match 2		-1		1	dB
EIN1	Output Noise Voltage 1	Rg = 600Ω , 20Hz to 22kHz		35	80	μV
EIN2	Output Noise Voltage 2	Rg = $600Ω$; Gv = $12dB$ 20Hz to $22kHz$		12	20	μV
SVR	Supply Voltage Rejection	$f = 100Hz$ to $10kHz$; $Vr = 1Vpk$; $Rg = 600\Omega$	50	60		dB
BW	Power Bandwidth		100			KHz
Asa	Stand-by Attenuation		90	110		dB
Isa	Stand-by Current			25	100	μΑ
Ам	Mute Attenuation		80	100		dB
Vos	Offset Voltage	Mute & Play	-100	0	100	mV
V_{AM}	Min. Supply Mute Threshold		7	7.5	8	V
T _{ON}	Turn on Delay	D2/D1 (IB1) 0 to 1		20	40	ms
T _{OFF}	Turn off Delay	D2/D1 (IB1) 1 to 0		20	40	ms
CD _{LK}	Clip Det High Leakage Current	CD off		0	15	μΑ
CD _{SAT}	Clip Det Sat. Voltage	CD on; I _{CD} = 1mA		150	300	mV
CD _{THD}	Clip Det THD level			1	2	%
TURNON	DIAGNOSTICS 1 (Power Amp	lifier Mode)				
Pgnd	Short to GND det. (below this limit, the Output is considered in Short Circuit to GND)	Power Amplifier in st-by condition			1.2	V
Pvs	Short to Vs det. (above this limit, the Output isconsidered in Short Circuit to Vs)		Vs -1.2			V
Pnop	Normal operation thresholds. (Within these limits, the Output is considered without faults).		1.8		Vs -1.8	V

ELECTRICAL CHARACTERISTICS (continued)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
Lsc	Shorted Load det.				0.5	Ω
Lop	Open Load det.		130			Ω
Lnop	Normal Load det.		1.5		70	Ω
TURN ON	DIAGNOSTICS 2 (Line Driver I	Mode)				
Pgnd	Short to GND det. (below this limit, the Output is considered in Short Circuit to GND)	Power Amplifier in st-by			1.2	V
Pvs	Short to Vs det. (above this limit, the Output isconsidered in Short Circuit to Vs)		Vs -1.2			V
Pnop	Normal operation thresholds. (Within these limits, the Output is considered without faults).		1.8		Vs -1.8	V
Lsc	Shorted Load det.				1.5	Ω
Lop	Open Load det.		400			Ω
Lnop	Normal Load det.		4.5		200	Ω
PERMANE	ENT DIAGNOSTICS 2 (Power A	Amplifier Mode or Line Driver N	Mode)			
Pgnd	Short to GND det. (below this limit, the Output is considered in Short Circuit to GND)	Power Amplifier in Mute or Play, one or more short circuits protection activated			1.2	V
Pvs	Short to Vs det. (above this limit, the Output is considered in Short Circuit to Vs)		Vs -1.2			V
Pnop	Normal operation thresholds. (Within these limits, the Output is considered without faults).		1.8		Vs -1.8	V
L _{SC}	Shorted Load det.	Power Amplifier mode			0.5	Ω
		Line Driver mode			1.5	Ω
Vo	Offset Detection	Power Amplifier in play, AC Input signals = 0	±1.5	2	±2.5	V
I ² C BUS IN	ITERFACE					
fscL	Clock Frequency			400		KHz
VIL	Input Low Voltage				1.5	V
ViH	Input High Voltage		2.3			V

Figure 2. Quiescent Current vs. Supply Voltage

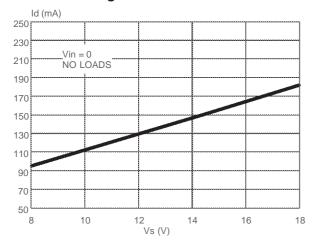


Figure 3. Output Power vs. Supply Voltage (4Ω)

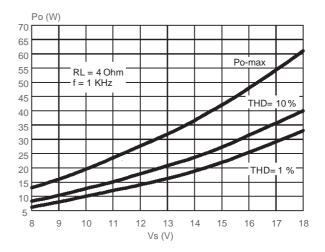


Figure 4. Output Power vs. Supply Voltage (2 Ω)

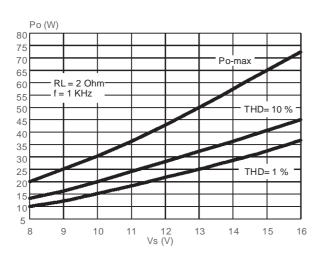


Figure 5. Distortion vs. Output Power (4Ω)

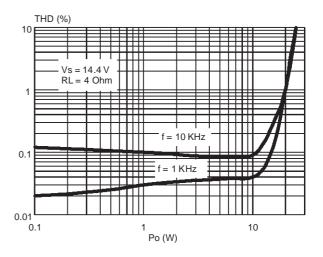


Figure 6. Distortion vs. Output Power (2 Ω)

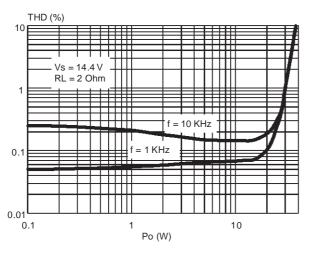
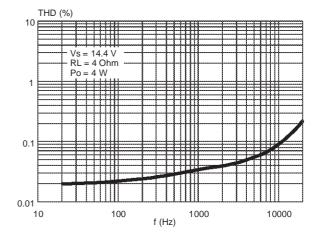


Figure 7. Distortion vs. Frequency (4 Ω)



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Figure 8. Distortion vs. Frequency (2 Ω)

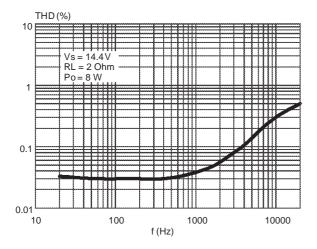


Figure 10. Supply Voltage Rejection vs. Frequency

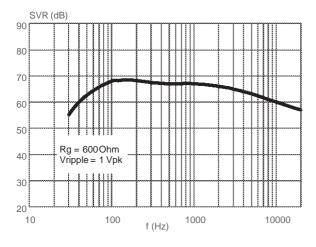


Figure 12. Power Dissipation vs. Average Ouput Power (Audio Program Simulation, 4Ω)

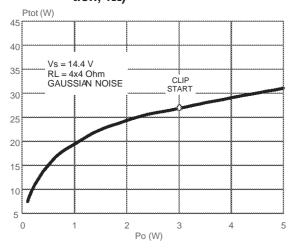


Figure 9. Crosstalk vs. Frequency

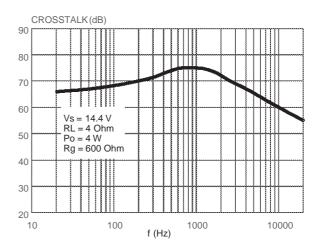


Figure 11. Power Dissipation & Efficiency vs. Output Power (4Ω , SINE)

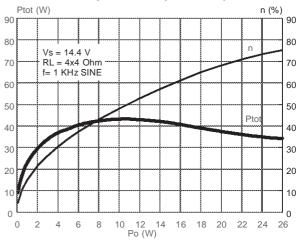
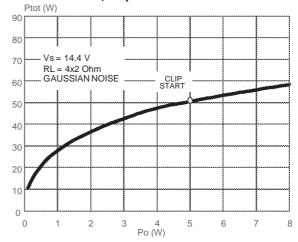


Figure 13. Power Dissipation vs. Average Ouput Power (Audio Program Simulation, 2Ω)



DIAGNOSTICS FUNCTIONAL DESCRIPTION: a) TURN-ON DIAGNOSTIC.

It is activated at the turn-on (stand-by out) under I2Cbus request. Detectable output faults are:

- SHORT TO GND
- SHORT TO Vs
- SHORT ACROSS THE SPEAKER
- OPEN SPEAKER

To verify if any of the above misconnections are in place, a subsonic (inaudible) current pulse (fig. 14) is internally generated, sent through the

speaker(s) and sunk back. The Turn On diagnostic status is internally stored until a successive diagnostic pulse is requested (after a I2C reading).

If the "stand-by out" and "diag. enable" commands are both given through a single programming step, the pulse takes place first (power stage still in stand-by mode, low, outputs= high impedance).

Afterwards, when the Amplifier is biased, the PERMANENT diagnostic takes place. The previous Turn On state is kept until a short appears at the outputs.

Figure 14. Turn - On diagnostic: working principle

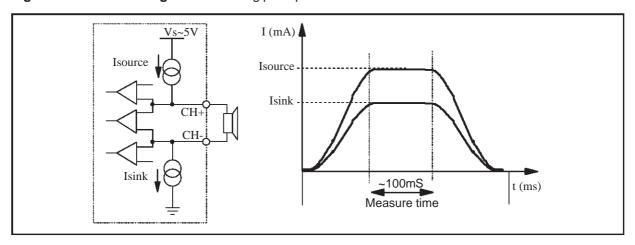


Fig. 15 and 16 show SVR and OUTPUT waveforms at the turn-on (stand-by out) with and without TURN-ON DIAGNOSTIC.

Figure 15. SVR and Output behaviour

CASE 1: without turn-on diagnostic

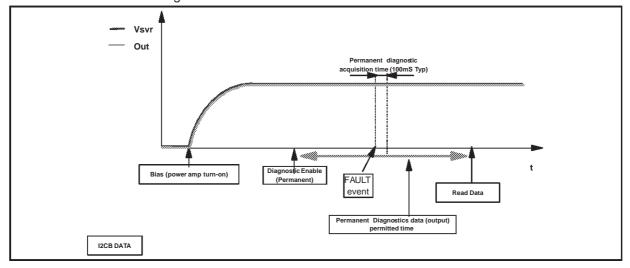
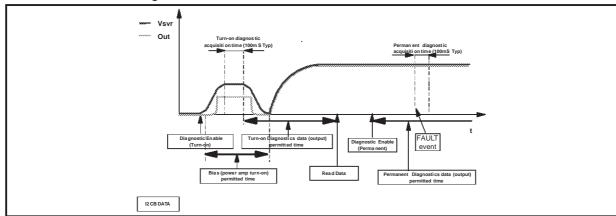
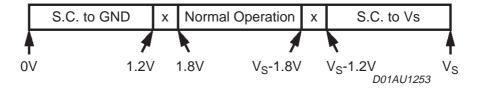


Figure 16. SVR and Output pin behaviour

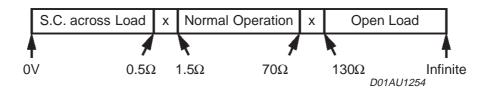
CASE 2: with turn-on diagnostic



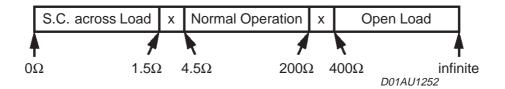
The information related to the outputs status is read and memorized at the end of the current pulse top. The acquisition time is 100 ms (typ.). No audible noise is generated in the process. As for SHORT TO GND / Vs the fault-detection thresholds remain unchanged from 26 dB to 12 dB gain setting. They are as follows:



Concerning SHORT ACROSS THE SPEAKER / OPEN SPEAKER, the threshold varies from 26 dB to 12 dB gain setting, since different loads are expected (either normal speaker's impedance or high impedance). The values in case of 26 dB gain are as follows:



If the Line-Driver mode (Gv= 12 dB and Line Driver Mode diagnostic = 1) is selected, the same thresholds will change as follows:



b) PERMANENT DIAGNOSTICS.

Detectable conventional faults are:

- SHORT TO GND
- SHORT TO Vs
- SHORT ACROSS THE SPEAKER

The following additional features are provided:

- OUTPUT OFFSET DETECTION

The TDA7561 has 2 operating statuses:

- 1) RESTART mode. The diagnostic is not enabled. Each audio channel operates independently from each other. If any of the a.m. faults occurs, only the channel(s) interested is shut down. A check of the output status is made every 1 ms (fig. 17). Restart takes place when the overload is removed.
- 2) DIAGNOSTIC mode. It is enabled via I²C bus and self activates if an output overload (such to cause the intervention of the short-circuit protection) occurs to the speakers outputs. Once acti-

vated, the diagnostics procedure develops as follows (fig. 18):

- To avoid momentary re-circulation spikes from giving erroneous diagnostics, a check of the output status is made after 1ms: if normal situation (no overloads) is detected, the diagnostic is not performed and the channel returns back active.
- -Instead, if an overload is detected during the check after 1 ms, then a diagnostic cycle having a duration of about 100 ms is started.
- -After a diagnostic cycle, the audio channel interested by the fault is switched to RESTART mode. The relevant data are stored inside the device and can be read by the microprocessor. When one cycle has terminated, the next one is activated by an I2C reading. This is to ensure continuous diagnostics throughout the car-radio operating time.
- -To check the status of the device a sampling system is needed. The timing is chosen at microprocessor level (over half a second is recommended).

Figure 17. Restart timing without Diagnostic Enable (Permanent)
Each 1mS time, a sampling of the fault is done

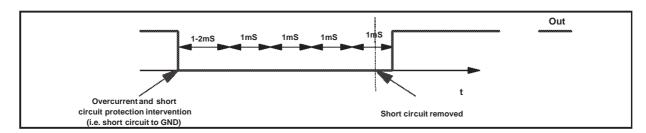
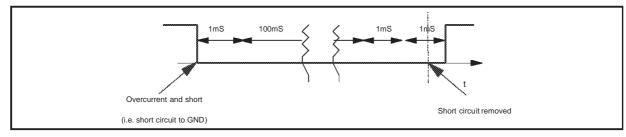


Figure 18. Restart timing with Diagnostic Enable (Permanent)



OUTPUT DC OFFSET DETECTION.

Any DC output offset exceeding +/- 2 V are signalled out. This inconvenient might occur as a consequence of initially defective or aged and worn-out input capacitors feeding a DC component to the inputs, so putting the speakers at risk of overheating.

This diagnostic has to be performed with low-level output AC signal (or Vin = 0).

The test is run with selectable time duration by microprocessor (from a "start" to a "stop" command):

START = Last reading operation or setting IB1 - D5 - (OFFSET enable) to 1

STOP = Actual reading operation

Excess offset is signalled out if persistent throughout the assigned testing time. This feature is disabled if any overloads leading to activation of the short-circuit protection occurs in the process.

MULTIPLE FAULTS.

When more misconnections are simultaneously in place at the audio outputs, it is guaranteed that at least one of them is initially read out. The others are notified after successive cycles of 1²C reading and faults removal, provided that the diagnostic is

enabled. This is true for both kinds of diagnostic (Turn on and Permanent).

The table below shows all the couples of possible double-fault. It should be taken into account that a short circuit with the 4 ohm speaker unconnected is considered as double fault.

Double fault table for Turn On Diagnostic							
	S. GND (so)	S. GND (sk)	S. Vs	S. Across L.	Open L.		
S. GND (so)	S. GND	S. GND	S. Vs + S. GND	S. GND	S. GND		
S. GND (sk)	/	S. GND	S. Vs	S. GND	Open L. (*)		
S. Vs	/	/	S. Vs	S. Vs	S. Vs		
S. Across L.	/	/	/	S. Across L.	N.A.		
Open L.	/	/	/	/	Open L. (*)		

S. GND (so) / S. GND (sk) in the above table make a distinction according to which of the 2 outputs is shorted to ground (test-current source side= so, test-current sink side = sk). More precisely, so = CH+, sk = CH-.

In Permanent Diagnostic the table is the same, with only a difference concerning Open Load(*), which is not among the recognisable faults. Should an Open Load be present during the device's normal working, it would be detected at a subsequent Turn on Diagnostic cycle (i.e. at the successive Car Radio Turn on).

FAULTS AVAILABILITY

All the results coming from I²Cbus, by read operations, are the consequence of measurements inside a defined period of time. If the fault is stable throughout the whole period, it will be sent out.

To guarantee always resident functions, every kind of diagnostic cycles (Turn on, Permanent, Offset) will be reactivate after any I²C reading operation. So, when the micro reads the I²C, a new cycle will be able to start, but the read data will come from the previous diag. cycle (i.e. The device is in Turn On state, with a short to Gnd, then the short is removed and micro reads I²C. The short to Gnd is still present in bytes, because it is

the result of the previous cycle. If another I^2C reading operation occurs, the bytes do not show the short). In general to observe a change in Diagnostic bytes, two I^2C reading operations are necessary.

I²C PROGRAMMING/READING SEQUENCE

A correct turn on/off sequence respectful of the diagnostic timings and producing no audible noises could be as follows (after battery connection):

TURN-ON: (STAND-BY OUT + DIAG ENABLE) - -- 500 ms (min) --- MUTING OUT

TURN-OFF: MUTING IN --- 20 ms --- (DIAG DIS-ABLE + STAND-BY IN)

Car Radio Installation: DIAG ENABLE (write) --- 200 ms --- I2C read (repeat until All faults disappear).

OFFSET TEST: Device in Play (no signal) -- OFFSET ENABLE - 30ms - I2C reading

(repeat I²C reading until high-offset message disappears).

I²C BUS INTERFACE

Data transmission from microprocessor to the TDA7561 and viceversa takes place through the 2 wires I²C BUS interface, consisting of the two lines SDA and SCL (pull-up resistors to positive supply voltage must be connected).

Data Validity

As shown by fig. 19, the data on the SDA line must be stable during the high period of the clock.

The HIGH and LOW state of the data line can only change when the clock signal on the SCL line is LOW.

Start and Stop Conditions

As shown by fig. 20 a start condition is a HIGH to LOW transition of the SDA line while SCL is HIGH.

The stop condition is a LOW to HIGH transition of the SDA line while SCL is HIGH.

Byte Format

Every byte transferred to the SDA line must contain 8 bits. Each byte must be followed by an acknowledge bit. The MSB is transferred first.

Acknowledge

The transmitter* puts a resistive HIGH level on the SDA line during the acknowledge clock pulse (see fig. 21). The receiver** the acknowledges has to pull-down (LOW) the SDA line during the acknowledge clock pulse, so that the SDAline is stable LOW during this clock pulse.

* Transmitter

- = master (μP) when it writes an address to the TDA7561
- = slave (TDA7561) when the μP reads a data byte from TDA7561

** Receiver

- = slave (TDA7561) when the μP writes an address to the TDA7561
- = master (μ P) when it reads a data byte from TDA7561

Figure 19: Data Validity on the I²CBUS

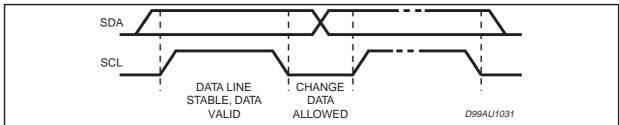


Figure 20: Timing Diagram on the I²CBUS

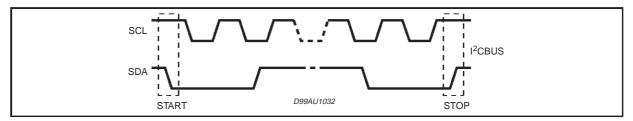
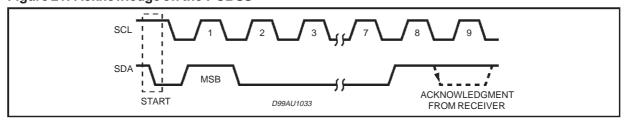


Figure 21: Acknowledge on the I²CBUS

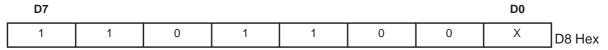


SOFTWARE SPECIFICATIONS

All the functions of the TDA7561 are activated by I²C interface.

The bit 0 of the "ADDRESS BYTE" defines if the next bytes are $\,$ write instruction (from μP to TDA7561) or read instruction (from TDA7561 to μP).

Chip Address:



X = 0 Write to device

X = 1 Read from device

If R/W = 0, the μ P sends 2 "Instruction Bytes": IB1 and IB2.

IB1

D7	X
D6	Diagnostic enable (D6 = 1) Diagnostic defeat (D6 = 0)
D5	Offset Detection enable (D5 = 1) Offset Detection defeat (D5 = 0)
D4	Front Channel Gain = 26dB (D4 = 0) Gain = 12dB (D4 = 1)
D3	Rear Channel Gain = 26dB (D3 = 0) Gain = 12dB (D3 = 1)
D2	Mute front channels (D2 = 0) Unmute front channels (D2 = 1)
D1	Mute rear channels (D1 = 0) Unmute rear channels (D1 = 1)
D0	X

IB2

D7	X
D6	used for testing
D5	used for testing
D4	Stand-by on - Amplifier not working - (D4 = 0) Stand-by off - Amplifier working - (D4 = 1)
D3	Power amplifier mode diagnostic (D3 = 0) Line driver mode diagnostic (D3 = 1)
D2	X
D1	X
D0	X

TDA7561

If R/W = 1, the TDA7561 sends 4 "Diagnostics Bytes" to μP : DB1, DB2, DB3 and DB4. **DB1**

D7	Thermal Warning active (D7 = 1)
D6	Diag. cycle not activated or not terminated (D6 = 0) Diag. cycle terminated (D6 = 1)
D5	X
D4	Channel LF Turn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)
D3	Channel LF Normal load (D3 = 0) Short load (D3 = 1)
D2	Channel LF Turn-on diag.: No open load (D2 = 0) Open load detection (D2 = 1) Offset diag.: No output offset (D2 = 0) Output offset detection (D2 = 1)
D1	Channel LF No short to Vcc (D1 = 0) Short to Vcc (D1 = 1)
D0	Channel LF No short to GND (D1 = 0) Short to GND (D1 = 1)

DB2

	,
D7	Offset detection not activated (D7 = 0) Offset detection activated (D7 = 1)
D6	X
D5	X
D4	Channel LR Turn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)
D3	Channel LR Normal load (D3 = 0) Short load (D3 = 1)
D2	Channel LR Turn-on diag.: No open load (D2 = 0) Open load detection (D2 = 1) Permanent diag.: No output offset (D2 = 0) Output offset detection (D2 = 1)
D1	Channel LR No short to Vcc (D1 = 0) Short to Vcc (D1 = 1)
D0	Channel LR No short to GND (D1 = 0) Short to GND (D1 = 1)

DB3

D7	Stand-by status (= IB1 - D4)
D6	Diagnostic status (= IB1 - D6)
D5	X
D4	Channel RF Turn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)
D3	Channel RF Normal load (D3 = 0) Short load (D3 = 1)
D2	Channel RF Turn-on diag.: No open load (D2 = 0) Open load detection (D2 = 1) Permanent diag.: No output offset (D2 = 0) Output offset detection (D2 = 1)
D1	Channel RF No short to Vcc (D1 = 0) Short to Vcc (D1 = 1)
D0	Channel RF No short to GND (D1 = 0) Short to GND (D1 = 1)

DB4

D7	X
D6	X
D5	X
D4	Channel RR Turn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)
D3	Channel RR Normal load (D3 = 0) Short load (D3 = 1)
D2	Channel RR Turn-on diag.: No open load (D2 = 0) Open load detection (D2 = 1) Permanent diag.: No output offset (D2 = 0) Output offset detection (D2 = 1)
D1	Channel RR No short to Vcc (D1 = 0) Short to Vcc (D1 = 1)
D0	Channel RR No short to GND (D1 = 0) Short to GND (D1 = 1)

Examples of bytes sequence

1 - Turn-On diagnostic - Write operation

2 - Turn-On diagnostic - Read operation

Start Add	ress byte with D0 = 1	ACK	DB1	ACK	DB2	ACK	DB3	ACK	DB4	ACK	STOP
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The delay from 1 to 2 can be selected by software, starting from T.B.D. ms

3a - Turn-On of the power amplifier with 26dB gain, mute on, diagnostic defeat.

Star	Address byte with D0 = 0	ACK	IB1	ACK	IB2	ACK	STOP
			X000000X		XXX1X0XX		

3b - Turn-Off of the power amplifier

Start	Start Address byte with D0 = 0 ACK		IB1	ACK	IB2	ACK	STOP
		X0XXXXXX		XXX0XXXX			

4 - Offset detection procedure enable

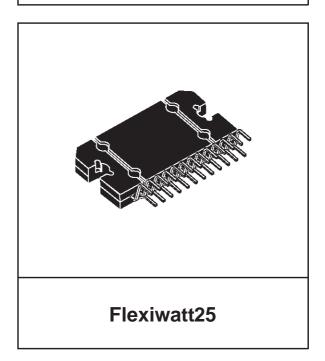
Start	Address byte with D0 = 0	ACK	IB1	ACK	IB2	ACK	STOP
			XX1XX11X		XXX1X0XX		

5 - Offset detection procedure stop and reading operation (the results are valid only for the offset detection bits (D2 of the bytes DB1, DB2, DB3, DB4).

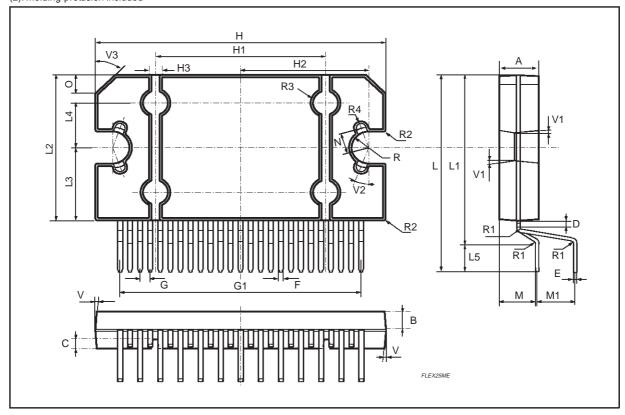
- The purpose of this test is to check if a D.C. offset (2V typ.) is present on the outputs, produced by input capacitor with anomalous leackage current or humidity between pins.
- The delay from 4 to 5 can be selected by software, starting from T.B.D. ms

DIM.		mm		inch					
DIIVI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.			
Α	4.45	4.50	4.65	0.175	0.177	0.183			
В	1.80	1.80 1.90		0.070	0.074	0.079			
С		1.40			0.055				
D	0.75	0.90	1.05	0.029	0.035	0.041			
E	0.37	0.39	0.42	0.014	0.015	0.016			
F (1)			0.57			0.022			
G	0.80	1.00	1.20	0.031	0.040	0.047			
G1	23.75	24.00	24.25	0.935	0.945	0.955			
H (2)	28.90	29.23	29.30	1.138	1.150	1.153			
H1		17.00			0.669				
H2		12.80			0.503				
H3		0.80			0.031				
L (2)	22.07	22.47	22.87	0.869	0.884	0.904			
L1	18.57	18.97	19.37	0.731	0.747	0.762			
L2 (2)	15.50	15.70	15.90	0.610	0.618	0.626			
L3	7.70	7.85	7.95	0.303	0.309	0.313			
L4		5			0.197				
L5		3.5			0.138				
M	3.70	4.00	4.30	0.145	0.157	0.169			
M1	3.60	4.00	4.40	0.142	0.157	0.173			
N		2.20			0.086				
0		2			0.079				
R		1.70			0.067				
R1		0.5			0.02				
R2		0.3			0.12				
R3		1.25			0.049				
R4	0.50 0.019								
V	5° (Typ.)								
V1	3° (Typ.)								
V2	20° (Typ.)								
V3	45° (Typ.)								

OUTLINE AND MECHANICAL DATA



(1): dam-bar protusion not included (2): molding protusion included



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